

ABSTRACT

An electronic module (2) and method for manufacturing same, the electronic module comprising a substrate (20) on which are disposed one or more electrically conductive tracks (21), at least one integrated circuit (22) comprising several bonding pads (22p), characterized in that it comprises:

- at least one intermediate bonding pad (25) situated on at least one face of said substrate (20),
- said intermediate bonding pad (25) is connected at least
- at a first point, to said electrically conductive tracks (21) or to a bonding well on the substrate (20), by means of a first bonding wire (241), and
- at a second point, to at least one pad of the integrated circuit (22), by means of a second bonding wire (242).

Figure for the abstract: fig. 1